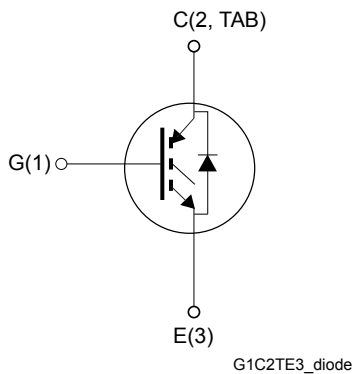
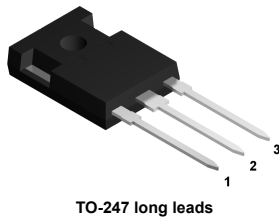



## Automotive-grade trench gate field-stop 650 V, 30 A low-loss M series IGBT in a TO-247 long leads package



### Features

- AEC-Q101 qualified 
- Maximum junction temperature:  $T_J = 175\text{ }^\circ\text{C}$
- 6  $\mu\text{s}$  of minimum short circuit withstand time
- Low  $V_{CE(sat)} = 1.7\text{ V (typ.) @ } I_C = 30\text{ A}$
- Tight parameter distribution
- Low thermal resistance
- Soft and very fast-recovery antiparallel diode

### Applications

- Motor control
- Auxiliary loads
- Thermal management
- General purpose inverter

### Description

This device is an IGBT developed using an advanced proprietary trench gate field-stop structure. The device is part of the M series IGBTs, which represent an optimal balance between inverter system performance and efficiency where the low-loss and the short-circuit functionality is essential.



#### Product status link

[STGWA30M65DF2AG](#)

#### Product summary

Order code	STGWA30M65DF2AG
Marking	G30M65DF2AG
Package	TO-247 long leads
Packing	Tube

# 1 Electrical ratings

**Table 1. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{CES}$	Collector-emitter voltage ( $V_{GE} = 0$ V)	650	V
$I_C$	Continuous collector current at $T_C = 25$ °C	87	A
	Continuous collector current at $T_C = 100$ °C	57	
$I_{CP}^{(1)}$	Pulsed collector current ( $t_p \leq 1$ $\mu$ s, $T_J < 175$ °C)	120	A
$V_{GE}$	Gate-emitter voltage	$\pm 20$	V
	Transient gate-emitter voltage ( $t_p \leq 10$ $\mu$ s, $D < 0.01$ )	$\pm 30$	
$I_F$	Continuous forward current at $T_C = 25$ °C	66	A
	Continuous forward current at $T_C = 100$ °C	40	
$I_{FP}^{(1)}$	Pulsed forward current	120	A
$P_{TOT}$	Total power dissipation at $T_C = 25$ °C	441	W
$T_{STG}$	Storage temperature range	-55 to 150	°C
$T_J$	Operating junction temperature range	-55 to 175	°C

1. Defined by  $R_{thJC}$  and limited by maximum junction temperature, not tested in production.

**Table 2. Thermal data**

Symbol	Parameter	Value	Unit
$R_{thJC}$	Thermal resistance, junction-to-case, IGBT	0.34	°C/W
	Thermal resistance, junction-to-case, diode	0.86	
$R_{thJA}$	Thermal resistance, junction-to-ambient	50	°C/W

## 2 Electrical characteristics

$T_J = 25\text{ °C}$  unless otherwise specified.

**Table 3. Static characteristics**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)CES}$	Collector-emitter breakdown voltage	$V_{GE} = 0\text{ V}$ , $I_C = 250\text{ }\mu\text{A}$	650			V
$V_{CE(sat)}$	Collector-emitter saturation voltage	$V_{GE} = 15\text{ V}$ , $I_C = 30\text{ A}$		1.60	2.0	V
		$V_{GE} = 15\text{ V}$ , $I_C = 30\text{ A}$ , $T_J = 125\text{ °C}$		1.85		
		$V_{GE} = 15\text{ V}$ , $I_C = 30\text{ A}$ , $T_J = 175\text{ °C}$		2.02		
$V_F$	Forward on-voltage	$I_F = 30\text{ A}$		1.86	2.65	V
		$I_F = 30\text{ A}$ , $T_J = 125\text{ °C}$		1.6		
		$I_F = 30\text{ A}$ , $T_J = 175\text{ °C}$		1.5		
$V_{GE(th)}$	Gate threshold voltage	$V_{CE} = V_{GE}$ , $I_C = 1\text{ mA}$	5	6	7	V
$I_{CES}$	Collector cut-off current	$V_{GE} = 0\text{ V}$ , $V_{CE} = 650\text{ V}$			25	$\mu\text{A}$
$I_{GES}$	Gate-emitter leakage current	$V_{CE} = 0\text{ V}$ , $V_{GE} = \pm 20\text{ V}$			$\pm 250$	nA

**Table 4. Dynamic characteristics**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{ies}$	Input capacitance	$V_{CE} = 25\text{ V}$ , $f = 1\text{ MHz}$ , $V_{GE} = 0\text{ V}$	-	2484	-	pF
$C_{oes}$	Output capacitance		-	148	-	pF
$C_{res}$	Reverse transfer capacitance		-	54	-	pF
$Q_g$	Total gate charge	$V_{CC} = 520\text{ V}$ , $I_C = 30\text{ A}$ , $V_{GE} = 0\text{ to }15\text{ V}$ (see Figure 26. Gate charge test circuit)	-	81.6	-	nC
$Q_{ge}$	Gate-emitter charge		-	20	-	nC
$Q_{gc}$	Gate-collector charge		-	36.6	-	nC

**Table 5. IGBT switching characteristics (inductive load)**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{CE} = 400\text{ V}$ , $I_C = 30\text{ A}$ , $V_{GE} = 15\text{ V}$ , $R_G = 10\ \Omega$ (see Figure 25. Test circuit for inductive load switching)		21.6	-	ns
$t_r$	Current rise time			24.5	-	ns
$di/dt_{(on)}$	Turn-on current slope			995	-	A/ $\mu$ s
$t_{d(off)}$	Turn-off delay time			138	-	ns
$t_f$	Current fall time			154	-	ns
$E_{on}^{(1)}$	Turn-on switching energy			756	-	$\mu$ J
$E_{off}^{(2)}$	Turn-off switching energy			1057	-	$\mu$ J
$t_{d(on)}$	Turn-on delay time	$V_{CE} = 400\text{ V}$ , $I_C = 30\text{ A}$ , $V_{GE} = 15\text{ V}$ , $R_G = 10\ \Omega$ , $T_J = 175\text{ }^\circ\text{C}$ (see Figure 25. Test circuit for inductive load switching)		21.2	-	ns
$t_r$	Current rise time			29.8	-	ns
$di/dt_{(on)}$	Turn-on current slope			838	-	A/ $\mu$ s
$t_{d(off)}$	Turn-off delay time			152.5	-	ns
$t_f$	Current fall time			266	-	ns
$E_{on}^{(1)}$	Turn-on switching energy			1334	-	$\mu$ J
$E_{off}^{(2)}$	Turn-off switching energy			1582	-	$\mu$ J
$t_{sc}$	Short-circuit withstand time	$V_{CC} = 400\text{ V}$ , $V_{GE} = 15\text{ V}$ , starting $T_J \leq 150\text{ }^\circ\text{C}$	6		-	$\mu$ s

1. Including the reverse recovery of the diode.

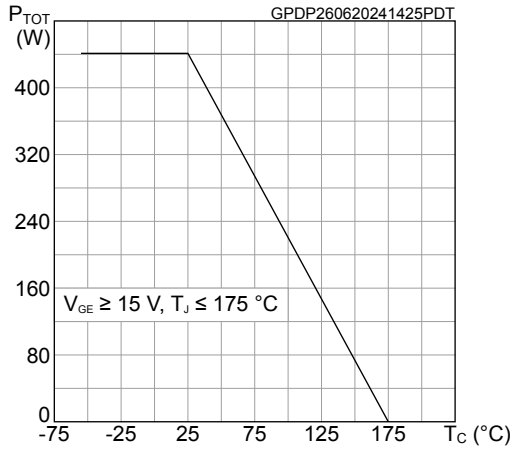
2. Including the tail of the collector current.

**Table 6. Diode switching characteristics (inductive load)**

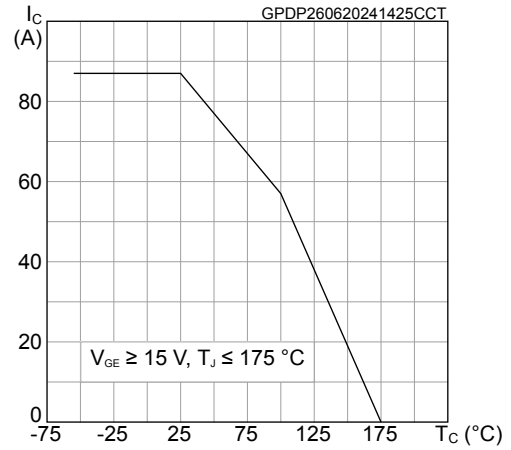
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit	
$t_{rr}$	Reverse recovery time	$I_F = 30\text{ A}$ , $V_R = 400\text{ V}$ , $V_{GE} = 15\text{ V}$ , $di/dt = 1000\text{ A}/\mu\text{s}$ (see Figure 25. Test circuit for inductive load switching)	-	151	-	ns	
$Q_{rr}$	Reverse recovery charge			-	0.78	-	$\mu$ C
$I_{rrm}$	Reverse recovery current			-	10.5	-	A
$dI_{rr}/dt$	Peak rate of fall of reverse recovery current during $t_b$			-	90	-	A/ $\mu$ s
$E_{rr}$	Reverse recovery energy			-	0.21	-	mJ
$t_{rr}$	Reverse recovery time	$I_F = 30\text{ A}$ , $V_R = 400\text{ V}$ , $V_{GE} = 15\text{ V}$ , $di/dt = 1000\text{ A}/\mu\text{s}$ , $T_J = 175\text{ }^\circ\text{C}$ (see Figure 25. Test circuit for inductive load switching)	-	239	-	ns	
$Q_{rr}$	Reverse recovery charge			-	2.4	-	$\mu$ C
$I_{rrm}$	Reverse recovery current			-	25.2	-	A
$dI_{rr}/dt$	Peak rate of fall of reverse recovery current during $t_b$			-	450	-	A/ $\mu$ s
$E_{rr}$	Reverse recovery energy			-	0.718	-	mJ

## 2.1 Electrical characteristics (curves)

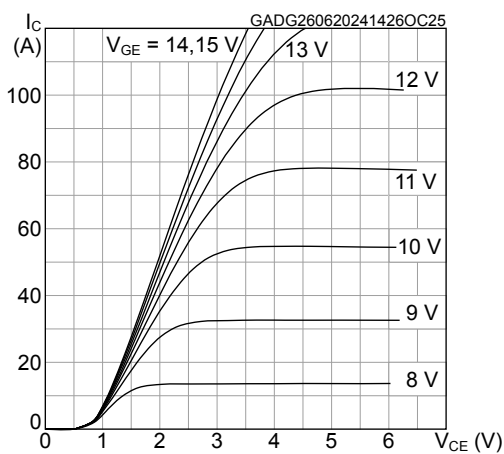
**Figure 1. Total power dissipation vs temperature**



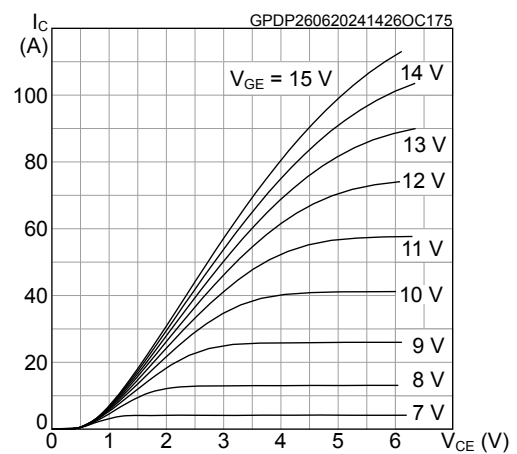
**Figure 2. Collector current vs temperature**



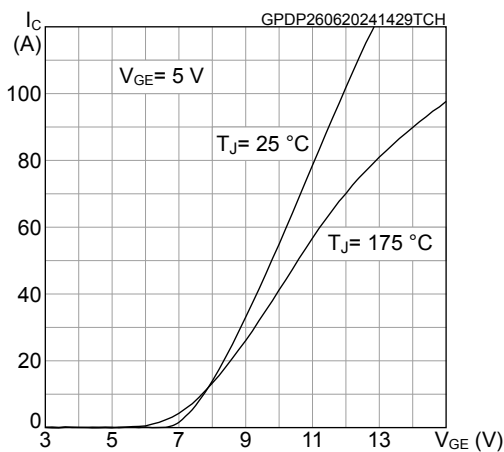
**Figure 3. Typical output characteristics ( $T_J = 25 \text{ }^\circ\text{C}$ )**



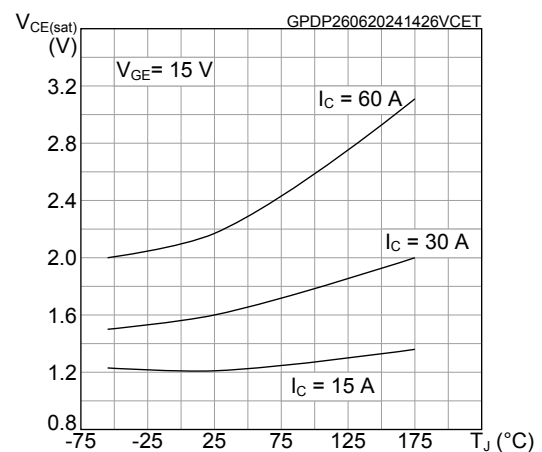
**Figure 4. Typical output characteristics ( $T_J = 175 \text{ }^\circ\text{C}$ )**



**Figure 5. Typical transfer characteristics**



**Figure 6. Typical  $V_{CE(sat)}$  vs temperature**



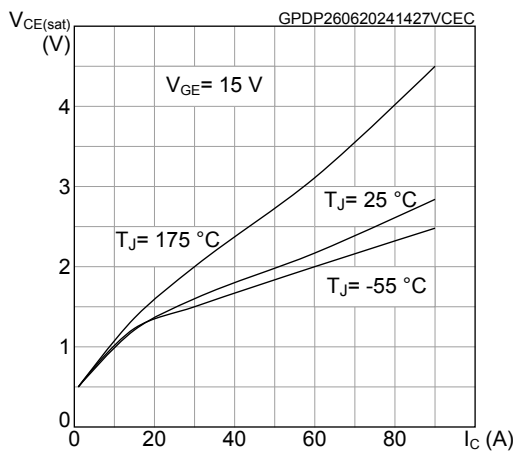
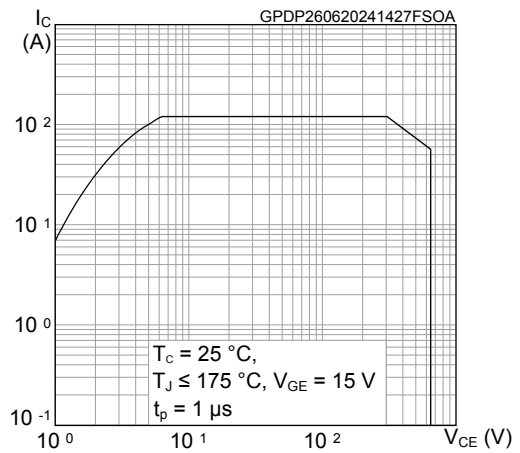
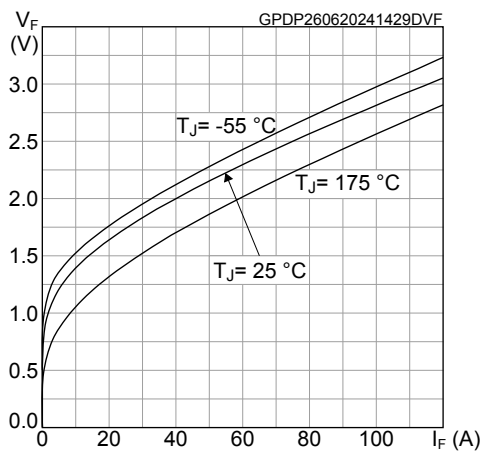
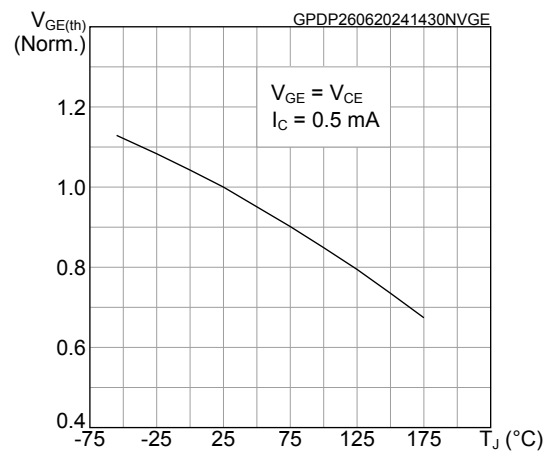
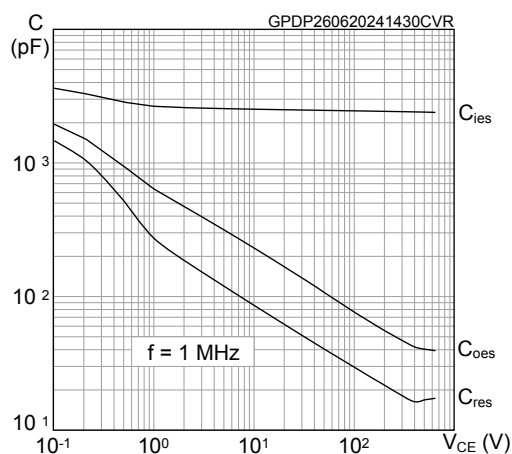
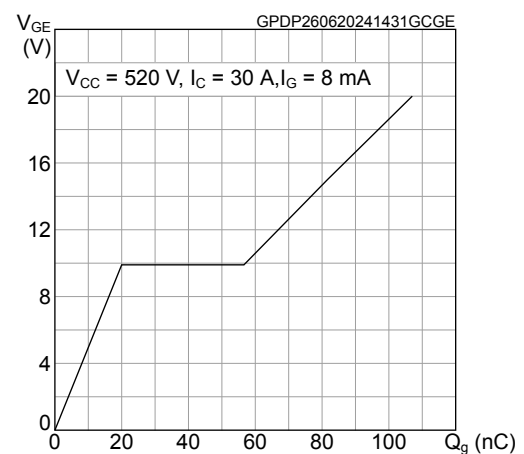
**Figure 7. Typical  $V_{CE(sat)}$  vs collector current**

**Figure 8. Forward bias safe operating area**

**Figure 9. Diode typical forward characteristics**

**Figure 10. Normalized gate threshold vs temperature**

**Figure 11. Typical capacitance characteristics**

**Figure 12. Typical gate charge characteristics**


Figure 13. Typical switching energy vs collector current

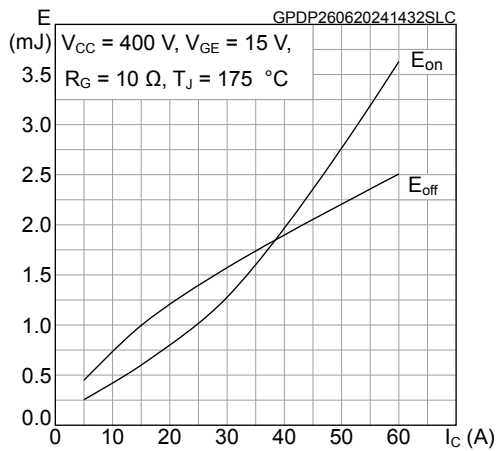


Figure 14. Typical switching energy vs temperature

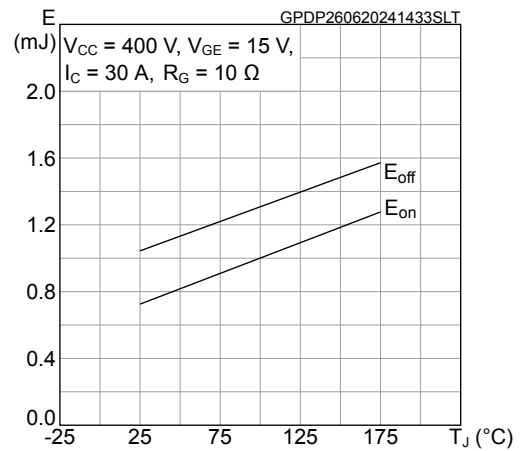


Figure 15. Typical switching energy vs supply voltage

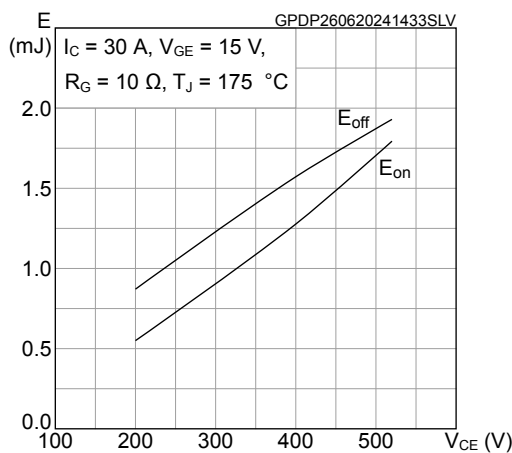


Figure 16. Typical switching energy vs gate resistance

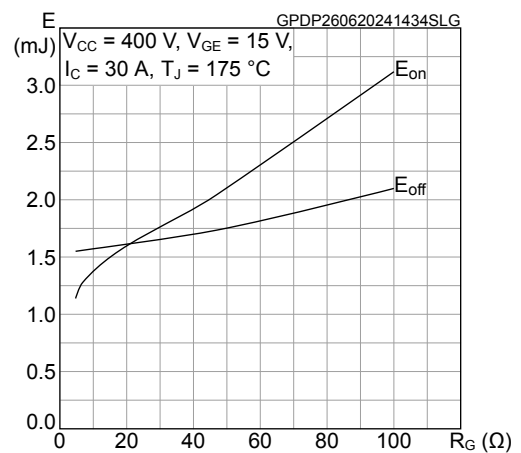


Figure 17. Typical switching times vs collector current

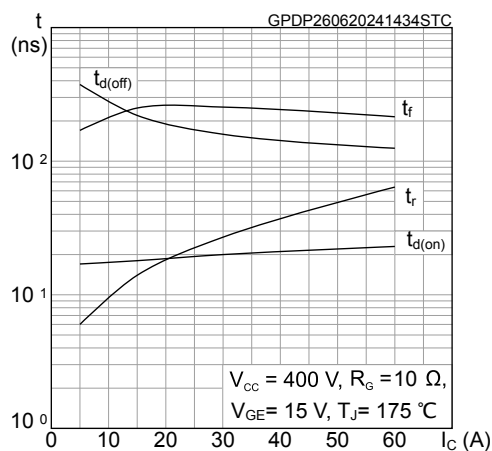
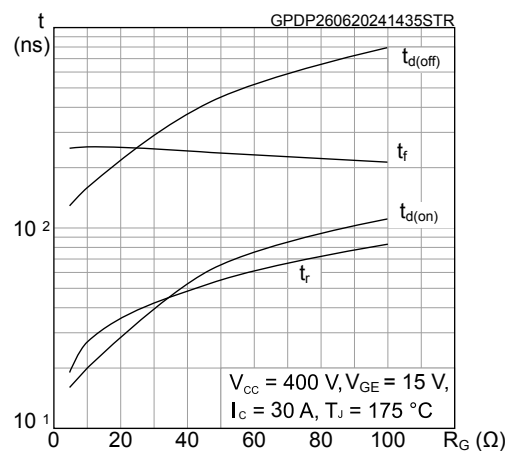
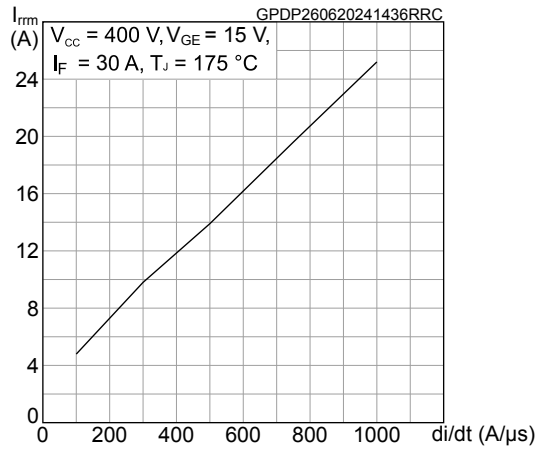
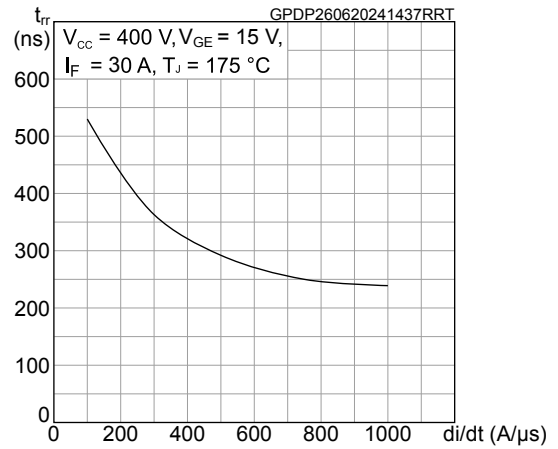
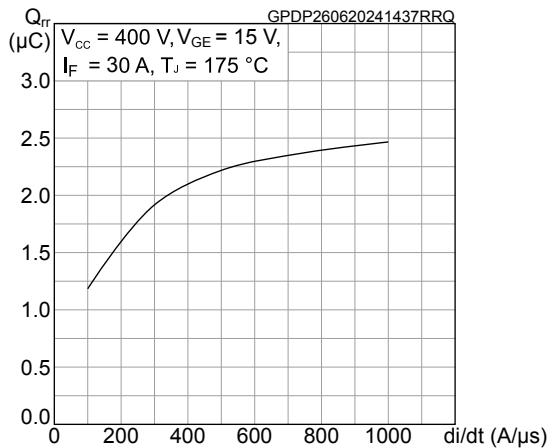
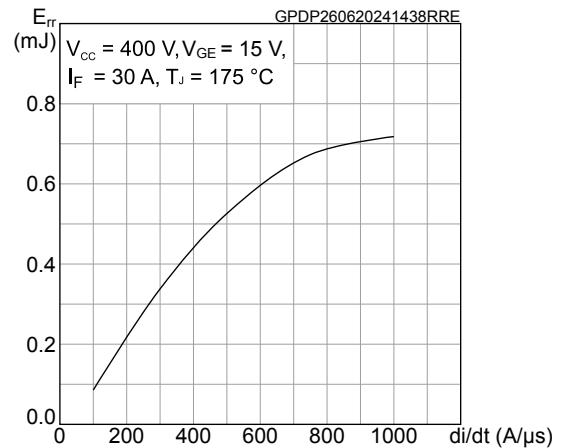
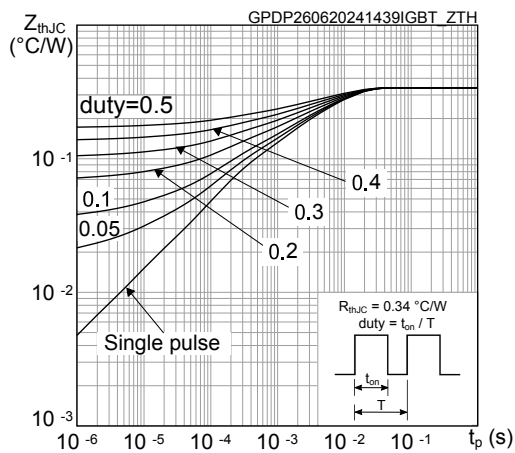
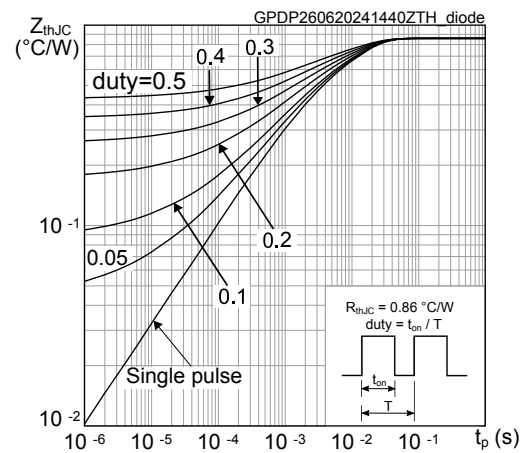


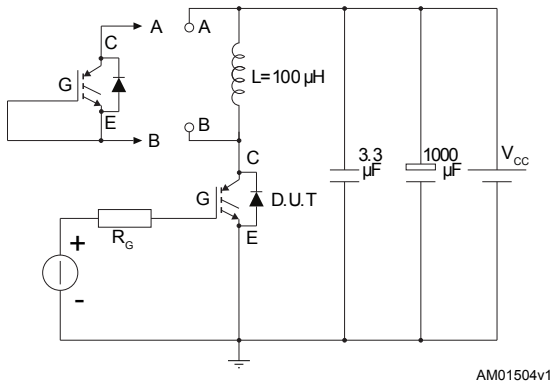
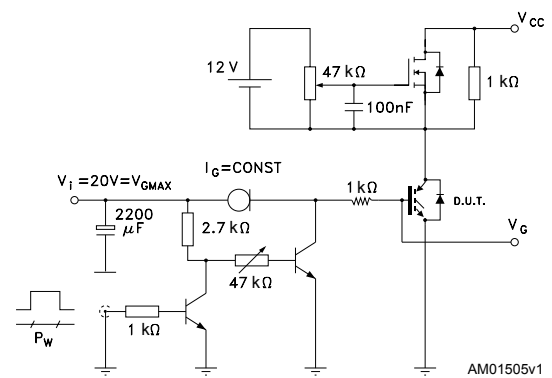
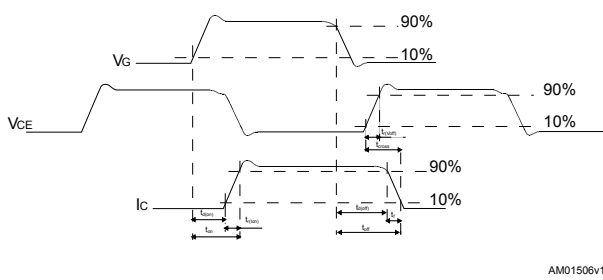
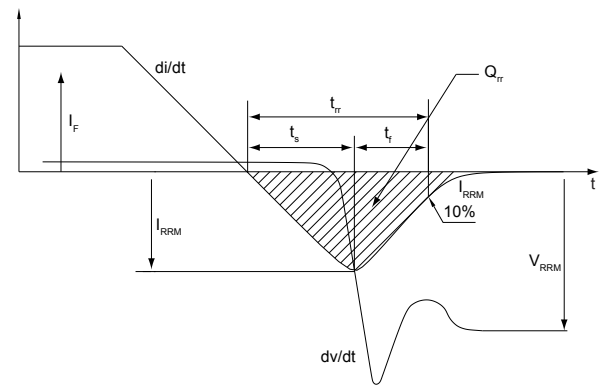
Figure 18. Typical switching times vs gate resistance



**Figure 19. Typical reverse recovery current vs diode current slope**

**Figure 20. Typical reverse recovery time vs diode current slope**

**Figure 21. Typical reverse recovery charge vs diode current slope**

**Figure 22. Typical reverse recovery energy vs diode current slope**

**Figure 23. IGBT maximum transient thermal impedance**

**Figure 24. Diode maximum transient thermal impedance**




### 3 Test circuits

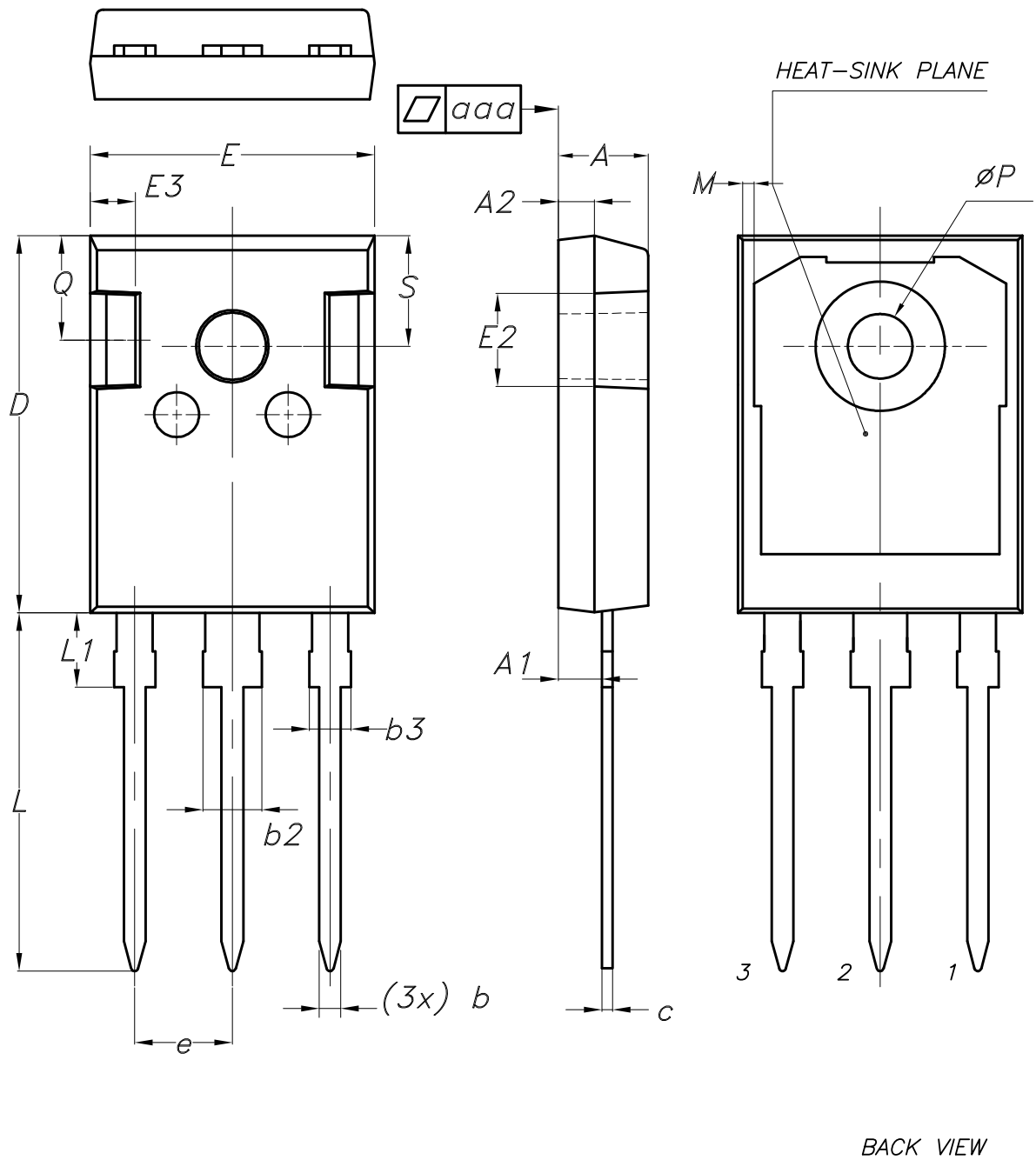
**Figure 25. Test circuit for inductive load switching**

**Figure 26. Gate charge test circuit**

**Figure 27. Switching waveform**

**Figure 28. Diode reverse recovery waveform**


## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

### 4.1 TO-247 long leads package information

Figure 29. TO-247 long leads package outline



BACK VIEW

8463846\_5

**Table 7. TO-247 long leads package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.90	5.00	5.10
A1	2.31	2.41	2.51
A2	1.90	2.00	2.10
b	1.16		1.26
b2			3.25
b3			2.25
c	0.59		0.66
D	20.90	21.00	21.10
E	15.70	15.80	15.90
E2	4.90	5.00	5.10
E3	2.40	2.50	2.60
e	5.34	5.44	5.54
L	19.80	19.92	20.10
L1			4.30
M	0.35		0.95
P	3.50	3.60	3.70
Q	5.60		6.00
S	6.05	6.15	6.25
aaa		0.04	0.10

## Revision history

**Table 8. Document revision history**

Date	Revision	Changes
20-May-2016	1	First release.
26-Jun-2023	2	Updated <i>Section 4.1 TO-247 long leads package information</i> . Minor text changes.
01-Jul-2024	3	Modified <i>Features and Description</i> . Modified <i>Section 1: Electrical ratings, Section 2: Electrical characteristics</i> . Added <i>Section 2.1: Electrical characteristics (curves)</i> . Minor text changes.

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<b>2</b>	<b>Electrical characteristics</b> .....	<b>3</b>
<b>2.1</b>	<b>Electrical characteristics (curves)</b> .....	<b>5</b>
<b>3</b>	<b>Test circuits</b> .....	<b>9</b>
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